

Descripción del producto

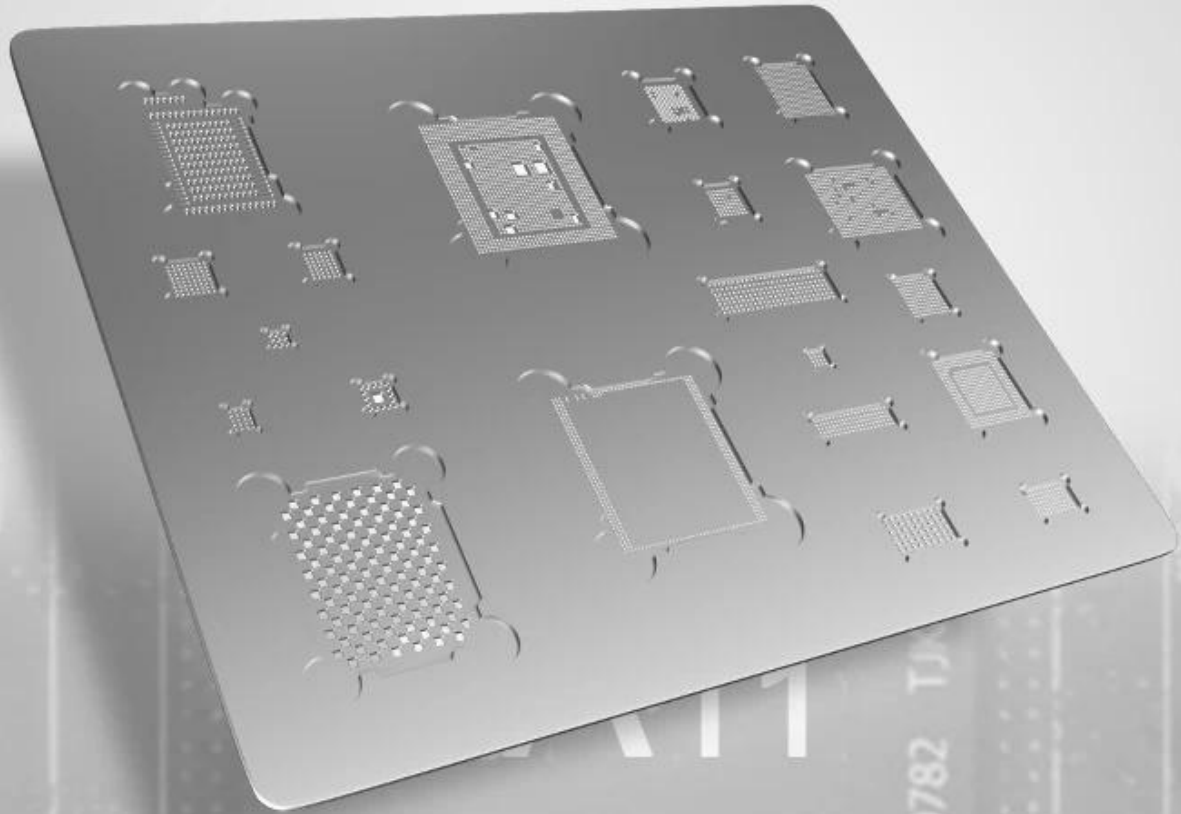
1. Hecho de acero importado.
2. Para iPhone, Samsung está disponible.

Muchos tipos están disponibles:

- 1x Plantillas BGA Reballing para iPhone X-XR-XS-XS Max
- 1x Plantillas BGA Reballing para iPhone 8Plus
- 1x Plantillas BGA Reballing para iPhone 8
- 1x Plantillas BGA Reballing para iPhone 7 Plus
- 1x Plantillas BGA Reballing para iPhone 7
- 1x Plantillas BGA Reballing para iPhone 6s Plus
- 1x plantillas BGA Reballing para iPhone 6s
- 1x Plantillas BGA Reballing para iPhone 6 Plus
- 1x Plantillas BGA Reballing para iPhone 6
- 1x Plantillas BGA Reballing para iPhone 5 SE
- 1x Plantillas BGA Reballing para iPhone 5s
- 1x BGA Reballing Stencils para iPhone 5c

3D GROOVE

— REBALLING STENCIL —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

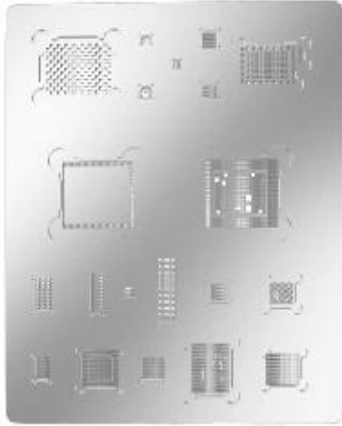


PRECISE ALIGNMENT



SQUARE HOLE

Product Usage



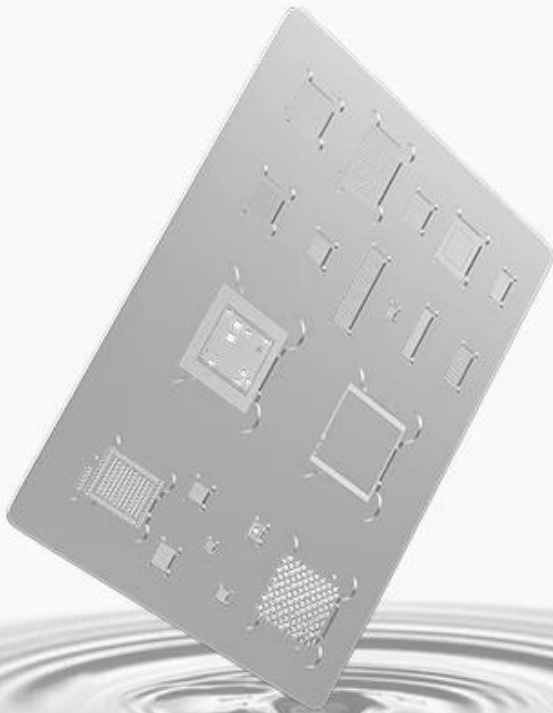
| | |
|-----------------------|----------------|
| MODEL | A11 |
| WEIGHT | 18.2g |
| MATERIAL | imported steel |
| SIZE | 68.9 X 84.9mm |
| MATCHING MACHINE TYPE | iPhone 8/8P/X |

▼ CHARACTERISTICS

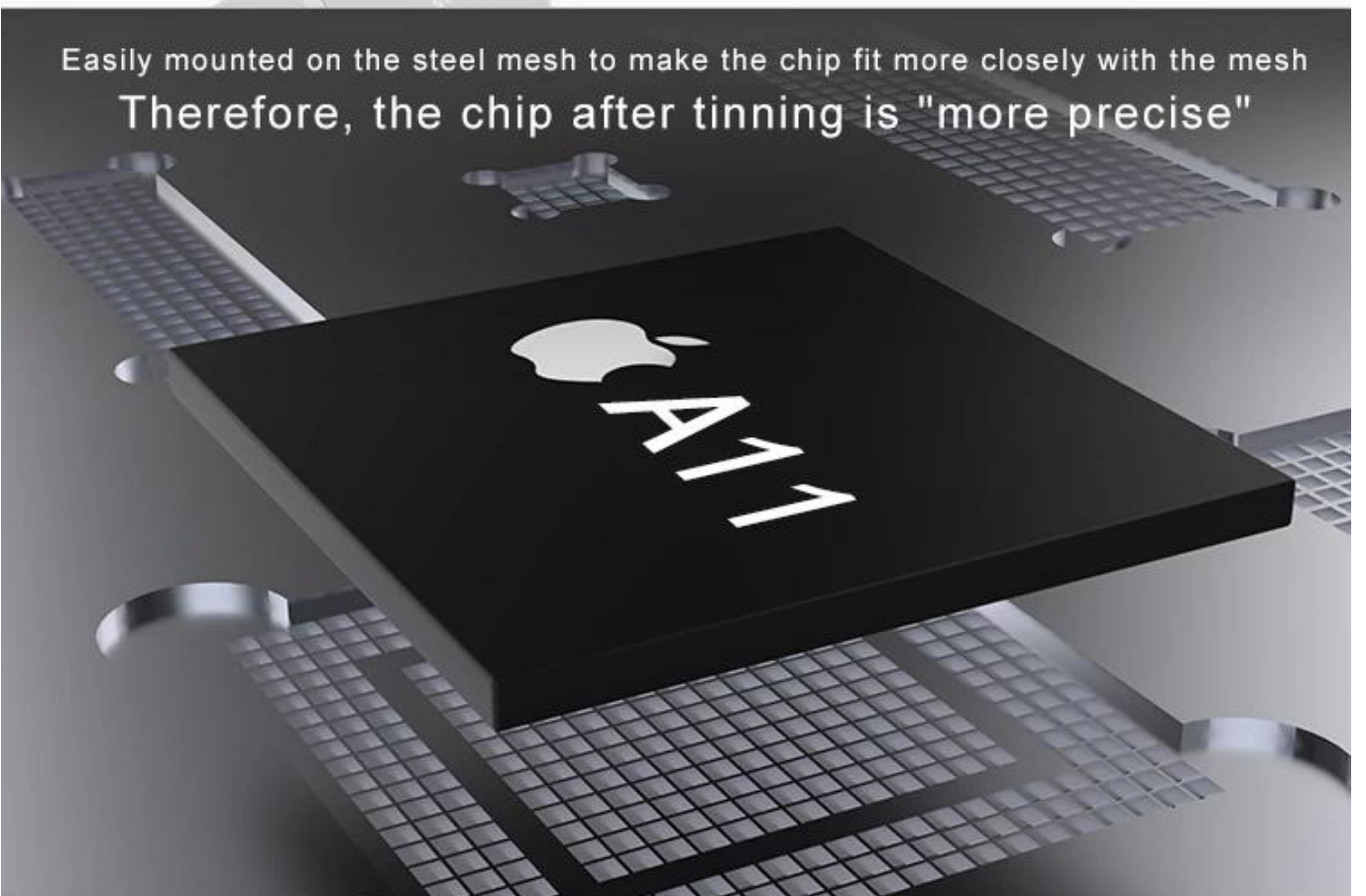
This product is used for BGA tinning repair of the iPhone8/8P/X series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

IMPORTED STEEL

HIGH TOUGHNESS



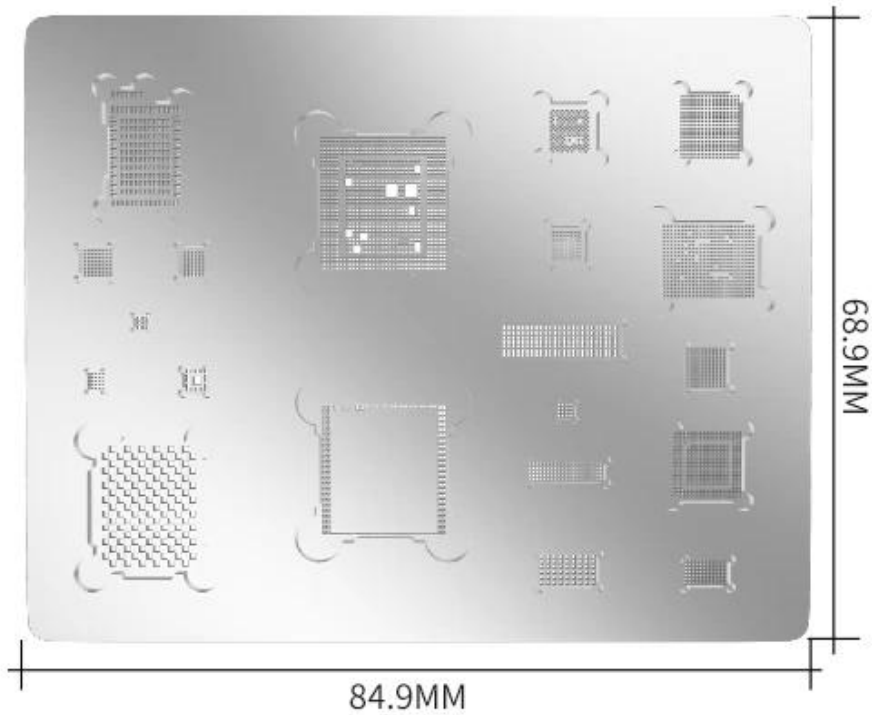
Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"





Imported steel
Hard and wear resistant
Accurate to the hole

PRODUCT SIZE



Thin to 0.30mm

Precise die-casting **form heating**



